

PRODUCT/PROCESS CHANGE NOTICE (PCN)				
PCN #: TB1902-01 Product Affected: F2932NBGP F2932NBGP8	Date: February 8, 2019	MEANS OF DISTINGUISHING CHANGED DEVICES: Product Mark Traceability to the test location is Back Mark maintained by IDT and available on Date Code request		
Date Effective: March 8, 2019		Other		
Contact: IDT PCN DESK		Attachment: Yes No		
E-mail: pcndesk@idt.co	<u>om</u>	Samples: Please contact your local sales representative for sample request.		
DESCRIPTION AND PURPOSE OF CHANGE:				
 Die Technology Wafer Fabrication Process Assembly Process Equipment Material Testing Manufacturing Site Data Sheet Other - Die Revision Change 		r customers that IDT is adding Sigurd, Taiwan as an alternate Test site for e. These parts are currently tested at the IDT Penang, Malaysia facility. details.		
RELIABILITY/QUALIFICATION SUMMARY: There is no expected change to the product quality or reliability performance. Please refer to page 2 for Electrical correlation data.				
to grant approval or request addition it will be assumed that this change	re written notification of this char nal information. If IDT does not is acceptable. r version manufactured after the p	nge. Please use the acknowledgement below or E-Mail receive acknowledgement within 30 days of this notice process change effective date until the inventory		
Customer:		Approval for shipments prior to effective date.		
Name/Date:		E-Mail Address:		
Title:		Phone # /Fax #:		
CUSTOMER COMMENTS:				
IDT ACKNOWLEDGMENT OF RECEIPT:				
RECD. BY:		DATE:		
	Pa	ge 1 of 2		



Integrated Device Technology, Inc. 6024 Silver Creek Valley Road, San Jose, CA 95138

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN# TB1902-01

PCN Type: Manufacturing Site - Alternate Test Location

Data Sheet Change: None

Detail of Change: Add Sigurd, Taiwan as an alternate Test site for the products listed on this notice. These parts are currently tested at the IDT Penang, Malaysia facility.

This change will allow IDT the flexibility to ship from either facility and will provide for the increase in capacity, flexibility and shorter lead time to meet market demand.

There is no change in the test flow or test coverage. Load boards are the same at both qualified facilities. IDT has completed the electrical test correlation and based on the test results we do not anticipate any impact on device performance. The testing is fully compatible and transferrable between the test facilities.

Electrical Test Correlation Results

Vehicle: F2932NBGP

Description	Existing Test (IDT Penang)	Alternate Test (Sigurd, Taiwan)
Tester Platform	J750	Ultraflex
Loadboard	F2932_J750_NGB16	F2932_LB1
Test Program	F2932_FT_125C.xls	F2932_UFlex_rev01.xls
Test Site	Penang	Sigurd
Test Temperature	125C	125C
Test Correlation Results between Sites	100%	100%
1. Good Units for Correlation	1000	1000
2. Good units, serialized with Datalog	10	10
3. Reject units, serialized with Datalog	5	5

Page 2 of 2